

# HLMP-DL50

T-1<sup>3</sup>/<sub>4</sub> (5 mm) Precision Optical Performance AlInGaP  
LED Lamps for Variable Message Signs



## Data Sheet

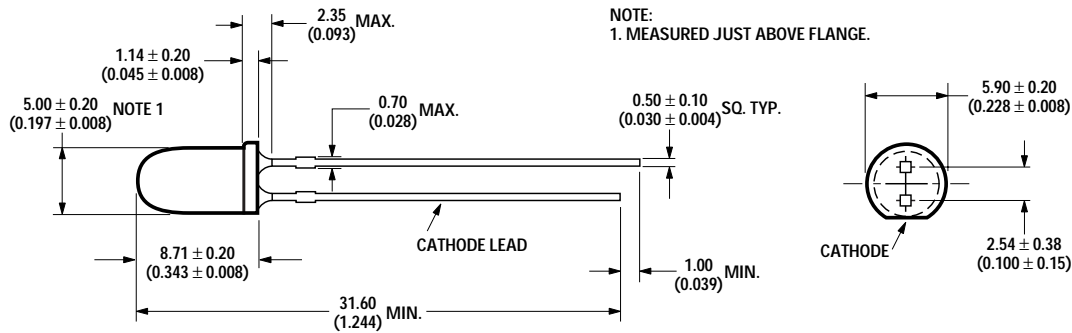
### Device Selection Guide

Part Number	Typical Viewing Angle $2\theta_{1/2}$ (Deg.)	Dominant Wavelength Range	Luminous Intensity (mcd at $I_F = 20$ mA) <sup>[1]</sup>
DL50	15	586.5 to 590.5 nm	4200 to 7200
DL51	15	588.5 to 592.5 nm	4200 to 7200

**Note:**

1. The luminous intensity is measured on the mechanical axis of the lamp package.

### Package Dimensions<sup>[2]</sup>



**Note:**

2. This part is only offered in a flanged package without stand-offs.

### Absolute Maximum Ratings at $T_A = 25^\circ\text{C}$

Parameter	Value
DC Forward Current <sup>[3, 4]</sup>	50 mA
Peak Pulsed Forward Current <sup>[3, 4]</sup>	100 mA
Average Forward Current <sup>[4]</sup>	30 mA
Reverse Voltage ( $I_R = 100 \mu\text{A}$ )	5 V
LED Junction Temperature	130°C
Operating Temperature	-40°C to +100°C
Storage Temperature	-40°C to +120°C

**Notes:**

- For long term performance with minimal light output degradation, drive currents between 10 and 30 mA are recommended.
- Please contact your sales representative about operating currents below 10 mA.

### Electrical/Optical Characteristics at $T_A = 25^\circ\text{C}$

Parameter	Symbol	Min.	Typical	Max.	Units	Test Conditions
Forward Voltage	$V_F$		2.02	2.4	V	$I_F = 20\text{ mA}$
Reverse Voltage	$V_R$	5	20		V	$I_R = 100\ \mu\text{A}$
Peak Wavelength	$\lambda_{\text{PEAK}}$		592		nm	Peak of Wavelength of Spectral Distribution at $I_F = 20\text{ mA}$
Spectral Halfwidth	$\Delta\lambda_{1/2}$		17		nm	Wavelength Width at Spectral Distribution $1/2$ Power point at $I_F = 20\text{ mA}$
Speed of Response	$t_s$		20		ns	Exponential Time Constant, $e^{-1/t_s}$
Capacitance	C		40		pF	$V_F = 0, f = 1\text{ MHz}$
Thermal Resistance	$R\theta_{\text{J-PIN}}$		240		$^\circ\text{C/W}$	LED Junction-to-Cathode Lead
Luminous Efficacy <sup>[5]</sup>	$\eta_V$		480		lm/W	Emitted Luminous Power/Emitted Radiant Power

**Note:**

5. The radiant intensity,  $I_e$ , in watts per steradian, may be found from the equation  $I_e = I_V/\eta_V$ , where  $I_V$  is the luminous intensity in candelas and  $\eta_V$  is the luminous efficacy in lumens/watt.

### Intensity Bin Limits (mcd at 20 mA)

Bin Name	Min.	Max.
V	4200	5500
W	5500	7200

**Note:**

6. Tolerance for each bin limit is  $\pm 15\%$ .

**Precautions**

**Lead Forming**

- The leads of an LED lamp may be preformed or cut to length prior to insertion and soldering into PC board.
- If lead forming is required before soldering, care must be taken to avoid any excessive mechanical stress induced to LED package. Otherwise, cut the leads of LED to length after soldering process at room temperature. The solder joint formed will absorb the mechanical stress of the lead cutting from traveling to the LED chip die attach and wirebond.
- It is recommended that tooling made to precisely form and cut the leads to length rather than rely upon hand operation.

**Soldering Conditions**

- Care must be taken during PCB assembly and soldering process to prevent damage to LED component.
- The closest LED is allowed to solder on board is 1.59 mm below the body (encapsulant epoxy) for those parts without standoff.
- Recommended soldering conditions:

	Wave Soldering	Manual Solder Dipping
Pre-heat Temperature	105 °C Max.	–
Pre-heat Time	30 sec Max.	–
Peak Temperature	250 °C Max.	260 °C Max.
Dwell Time	3 sec Max.	5 sec Max.

- Wave soldering parameter must be set and maintained according to recommended temperature and dwell time in the solder wave. Customer is advised to periodically check on the soldering profile to ensure the soldering profile used is always conforming to recommended soldering condition.
- If necessary, use fixture to hold the LED component in proper orientation with respect to the PCB during soldering process.
- Proper handling is imperative to avoid excessive thermal stresses to LED components when heated. Therefore, the soldered PCB must be allowed to cool to room temperature, 25°C, before handling.
- Special attention must be given to board fabrication, solder masking, surface plating and lead holes size and component orientation to assure solderability.
- Recommended PC board plated through hole sizes for LED component leads:

LED Component Lead Size	Diagonal	Plated Through Hole Diameter
0.457 x 0.457 mm (0.018 x 0.018 inch)	0.646 mm (0.025 inch)	0.976 to 1.078 mm (0.038 to 0.042 inch)
0.508 x 0.508 mm (0.020 x 0.020 inch)	0.718 mm (0.028 inch)	1.049 to 1.150 mm (0.041 to 0.045 inch)

**Note:** Refer to application note AN1027 for more information on soldering LED components.

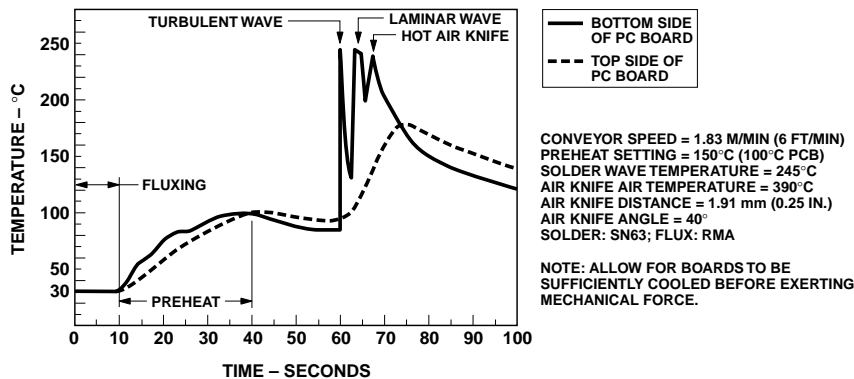


Figure 1. Recommended wave soldering profile.

For product information and a complete list of distributors, please go to our website: [www.avagotech.com](http://www.avagotech.com)

Avago, Avago Technologies, and the A logo are trademarks of Avago Technologies Limited in the United States and other countries.  
Data subject to change. Copyright © 2006 Avago Technologies Limited. All rights reserved. Obsoletes 5989-2894EN  
5989-4365EN May 21, 2006

